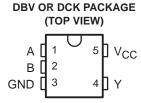
SCES213O - APRIL 1999 - REVISED SEPTEMBER 2003

- Available in the Texas Instruments
 NanoStar™ and NanoFree™ Packages
- Supports 5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 3.6 ns at 3.3 V
- Low Power Consumption, 10-μA Max I_{CC}
- ±24-mA Output Drive at 3.3 V
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)



YEA, YEP, YZA, OR YZP PACKAGE (BOTTOM VIEW)



description/ordering information

This single 2-input positive-NOR gate is designed for 1.65-V to 5.5-V V_{CC} operation.

The SN74LVC1G02 performs the Boolean function $Y = \overline{A + B}$ or $Y = \overline{A} \bullet \overline{B}$ in positive logic.

NanoStar™ and NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION

| TA | PACKAGE [†] | | ORDERABLE PART NUMBER | TOP-SIDE MARKING‡ |
|---------------|--|--------------|--------------------------|----------------------|
| | NanoStar™ – WCSP (DSBGA) 0.17-mm Small Bump – YEA | | SN74LVC1G02YEAR | |
| | NanoFree™ – WCSP (DSBGA) 0.17-mm Small Bump – YZA (Pb-free) | Reel of 3000 | SN74LVC1G02YZAR | СВ |
| | NanoStar™ – WCSP (DSBGA) 0.23-mm Large Bump – YEP | Reel of 3000 | SN74LVC1G02YEPR | OB_ |
| −40°C to 85°C | NanoFree™ – WCSP (DSBGA) 0.23-mm Large Bump – YZP (Pb-free) | | SN74LVC1G02YZPR | |
| | SOT (SOT-23) – DBV | Reel of 3000 | SN74LVC1G02DBVR | C02 |
| | 301 (301-23) = DBV | Reel of 250 | SN74LVC1G02DBVT | C02_ |
| | SOT (SC-70) – DCK | Reel of 3000 | SN74LVC1G02DCKR | СВ |
| | 301 (30-70) - DCK | Reel of 250 | SN74LVC1G02DCKT | CD_ |

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

DBV/DCK: The actual top-side marking has one additional character that designates the assembly/test site.

YEA/YZA,YEP/YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

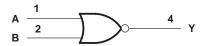
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TEXAS INSTRUMENTS
POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

FUNCTION TABLE

| INP | UTS | OUTPUT |
|-----|-----|--------|
| Α | В | Y |
| Н | Χ | L |
| X | Н | L |
| L | L | Н |

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

| Supply voltage range, V _{CC} | |
|---|---|
| Voltage range applied to any output in the high-impedance or power-off state, V _O (see Note 1) | –0.5 V to 6.5 V |
| Voltage range applied to any output in the high or low state, VO | |
| (see Notes 1 and 2) | $0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$ |
| Input clamp current, I _{IK} (V _I < 0) | |
| Output clamp current, I _{OK} (V _O < 0) | |
| Continuous output current, I _O | |
| Continuous current through V _{CC} or GND | |
| Package thermal impedance, θ _{JA} (see Note 3): DBV package | |
| DCK package | |
| YEA/YZA package | |
| YEP/YZP package | |
| Storage temperature range, T _{stq} | |

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. The value of $V_{\hbox{CC}}$ is provided in the recommended operating conditions table.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 4)

| | | | MIN | MAX | UNIT | |
|---------------------|------------------------------------|--|------------------------|------------------------|------|--|
| V | Supply voltage | Operating | 1.65 | 5.5 | V | |
| VCC | Supply voltage | Data retention only | 1.5 | | V | |
| | | V _{CC} = 1.65 V to 1.95 V | 0.65 × V _{CC} | | | |
| \/ | High-level input voltage | $V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$ | 1.7 | | V | |
| VIH | nigii-ievei iriput voitage | V _{CC} = 3 V to 3.6 V | 2 | | v | |
| | | $V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$ | 0.7 × V _{CC} | | | |
| | | V _{CC} = 1.65 V to 1.95 V | | 0.35 × V _{CC} | | |
| \/ | Low level input voltage | $V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$ | | 0.7 | V | |
| VIL | Low-level input voltage | V _{CC} = 3 V to 3.6 V | | 0.8 | V | |
| | | V _{CC} = 4.5 V to 5.5 V | | 0.3 × V _{CC} | | |
| ٧ _I | Input voltage | | 0 | 5.5 | V | |
| ۷o | Output voltage | | 0 | VCC | V | |
| | | V _{CC} = 1.65 V | | -4 | | |
| | | V _{CC} = 2.3 V | | -8 | | |
| loh | High-level output current | V 2V | | -16 | mA | |
| | | VCC = 3 V | | -24 | | |
| | | V _{CC} = 4.5 V | | -32 | | |
| | | V _{CC} = 1.65 V | | 4 | | |
| | | V _{CC} = 2.3 V | | 8 | | |
| I_{OL} | Low-level output current | V 2V | | 16 | mA | |
| | | VCC = 3 V | | 24 | | |
| | | V _{CC} = 4.5 V | | 32 | | |
| | | V_{CC} = 1.8 V ± 0.15 V, 2.5 V ± 0.2 V | | 20 | | |
| $\Delta t/\Delta v$ | Input transition rise or fall rate | $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$ | | 10 | ns/V | |
| | | V _{CC} = 5 V ± 0.5 V | | 5 | | |
| TA | Operating free-air temperature | <u> </u> | -40 | 85 | °C | |

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PAF | RAMETER | TEST CONDITIONS | | VCC | MIN | TYP [†] | MAX | UNIT | |
|------------------|---------------|---|------------------------|-----------------|----------------------|------------------|--------------|------|--|
| | | $I_{OH} = -100 \mu A$ | | 1.65 V to 5.5 V | V _{CC} -0.1 | | | | |
| | | $I_{OH} = -4 \text{ mA}$ | 1.65 V | 1.2 | | | | | |
| ١., | | $I_{OH} = -8 \text{ mA}$ | 2.3 V | 1.9 | | | V | | |
| VOH | | $I_{OH} = -16 \text{ mA}$ | | 2.1/ | 2.4 | | | V | |
| | | I _{OH} = -24 mA | 3 V | 2.3 | | | 1 1 | | |
| | | I _{OH} = -32 mA | 4.5 V | 3.8 | | | | | |
| | | I _{OL} = 100 μA | | 1.65 V to 5.5 V | | | 0.1 | | |
| | | I _{OL} = 4 mA | 1.65 V | | | 0.45 |] | | |
| \ \/ - · | | $I_{OL} = 8 \text{ mA}$ | 2.3 V | 0.3 | | | _v | | |
| VOL | | $I_{OL} = 16 \text{ mA}$ | | 2.1/ | | | 0.4 | V | |
| | | $I_{OL} = 24 \text{ mA}$ | | 3 V | | | 0.55 | | |
| | | I _{OL} = 32 mA | | 4.5 V | | | 0.55 | | |
| Ц | A or B inputs | V _I = 5.5 V or GND | | 0 to 5.5 V | | | ±5 | μА | |
| l _{off} | | V_I or $V_O = 5.5 V$ | | 0 | | | ±10 | μΑ | |
| ICC | | $V_I = 5.5 \text{ V or GND}, \qquad I_O = 0$ | | 1.65 V to 5.5 V | | | 10 | μΑ | |
| ∆lcc | | One input at $V_{CC} - 0.6 \text{ V}$, Other inputs at | V _{CC} or GND | 3 V to 5.5 V | | | 500 | μΑ | |
| Ci | | $V_I = V_{CC}$ or GND | | 3.3 V | | 4 | | pF | |

 $[\]dagger$ All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

switching characteristics over recommended operating free-air temperature range, C_L = 15 pF (unless otherwise noted) (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | V _{CC} = | | V _{CC} = ± 0. | | V _{CC} = | | V _{CC} ± 0. | | UNIT |
|-----------------|-----------------|----------------|-------------------|-----|------------------------|-----|-------------------|-----|----------------------|-----|------|
| | (1141 01) | (0011 01) | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | |
| ^t pd | A or B | Υ | 1.9 | 7.2 | 0.8 | 4.4 | 0.8 | 3.6 | 0.8 | 3.4 | ns |

switching characteristics over recommended operating free-air temperature range, C_L = 30 pF or 50 pF (unless otherwise noted) (see Figure 2)

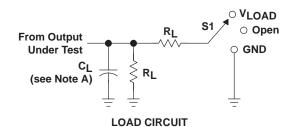
| PARAMETER FROM (INPUT) | | TO (OUTPUT) | | V _{CC} = 1.8 V ± 0.15 V | | V _{CC} = 2.5 V ± 0.2 V | | V _{CC} = 3.3 V ± 0.3 V | | V _{CC} = 5 V ± 0.5 V | |
|------------------------|-----------|----------------|-----|-------------------------------------|-----|------------------------------------|-----|------------------------------------|-----|----------------------------------|----|
| | (IIVI O1) | (0011 01) | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | |
| ^t pd | A or B | Υ | 2.8 | 8 | 1.2 | 5.5 | 1 | 4.5 | 1 | 4 | ns |

operating characteristics, T_A = 25°C

| PARAMETER | | TEST CONDITIONS | V _{CC} = 1.8 V | V _{CC} = 2.5 V | V _{CC} = 3.3 V | V _{CC} = 5 V | UNIT | |
|-----------------|-------------------------------|-----------------|-------------------------|-------------------------|-------------------------|-----------------------|------|--|
| | PARAMETER | TEST CONDITIONS | TYP | | TYP | TYP | UNIT | |
| C _{pd} | Power dissipation capacitance | f = 10 MHz | 23 | 23 | 23 | 25 | pF | |

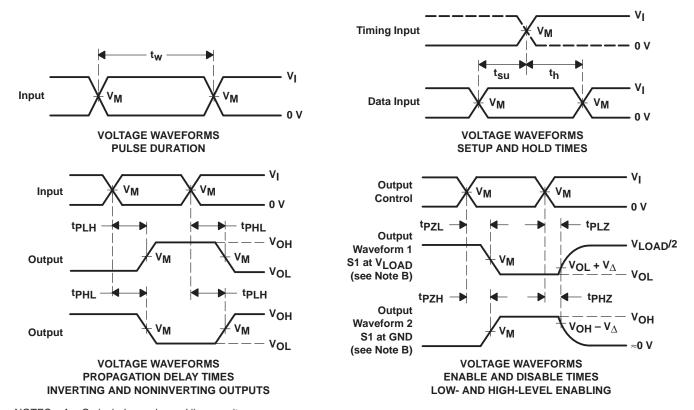


PARAMETER MEASUREMENT INFORMATION



| TEST | S 1 |
|-----------|-------------------|
| tPLH/tPHL | Open |
| tPLZ/tPZL | V _{LOAD} |
| tPHZ/tPZH | GND |

| ., | INF | PUTS | | VM VLOAD | | _ | ., |
|-------------------|----------------|--------------------------------|--------------------|-------------------|-------|--------------|-----------------------|
| VCC | ٧ _I | t _r /t _f | VM | VLOAD | CL | RL | $oldsymbol{V}_\Delta$ |
| 1.8 V ± 0.15 V | VCC | ≤2 ns | V _{CC} /2 | 2×V _{CC} | 15 pF | 1 M Ω | 0.15 V |
| 2.5 V \pm 0.2 V | VCC | ≤ 2 ns | V _{CC} /2 | 2×V _{CC} | 15 pF | 1 M Ω | 0.15 V |
| 3.3 V \pm 0.3 V | 3 V | ≤2.5 ns | 1.5 V | 6 V | 15 pF | 1 M Ω | 0.3 V |
| 5 V \pm 0.5 V | VCC | ≤2.5 ns | V _{CC} /2 | 2×V _{CC} | 15 pF | 1 M Ω | 0.3 V |



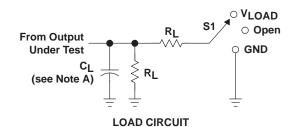
NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_Ω = 50 Ω.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

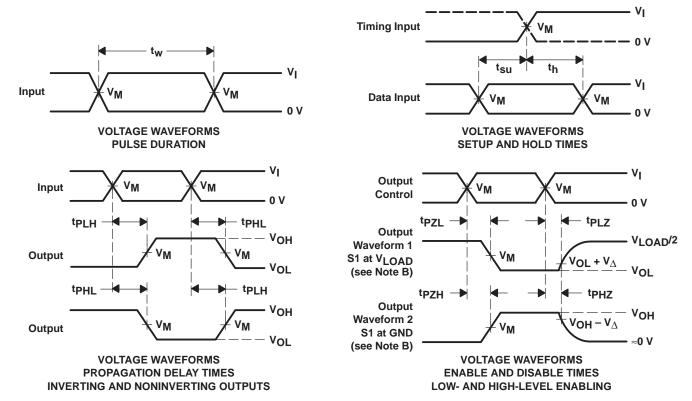


PARAMETER MEASUREMENT INFORMATION



| TEST | S 1 |
|-----------|-------------------|
| tPLH/tPHL | Open |
| tPLZ/tPZL | V _{LOAD} |
| tPHZ/tPZH | GND |

| ., | INF | PUTS | ., | ., | • | - | ., |
|-------------------|----------------|--------------------------------|--------------------|-------------------|-------|--------------|------------|
| VCC | ٧ _I | t _r /t _f | VM | VLOAD | CL | RL | V_Δ |
| 1.8 V ± 0.15 V | VCC | ≤2 ns | V _{CC} /2 | 2×V _{CC} | 30 pF | 1 k Ω | 0.15 V |
| 2.5 V \pm 0.2 V | VCC | ≤2 ns | V _{CC} /2 | 2×V _{CC} | 30 pF | 500 Ω | 0.15 V |
| 3.3 V \pm 0.3 V | 3 V | ≤2.5 ns | 1.5 V | 6 V | 50 pF | 500 Ω | 0.3 V |
| 5 V \pm 0.5 V | VCC | ≤2.5 ns | V _{CC} /2 | 2×V _{CC} | 50 pF | 500 Ω | 0.3 V |



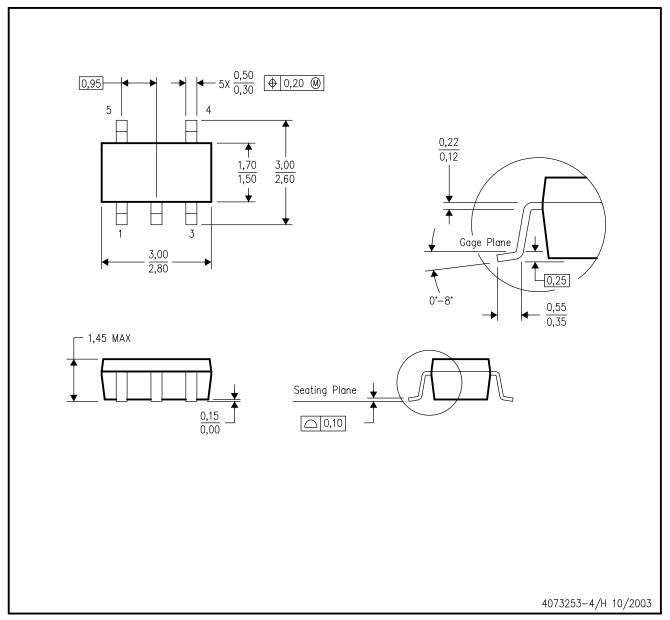
- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. tpzL and tpzH are the same as ten.
 - G. tplH and tpHL are the same as tpd.
 - H. All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms



DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



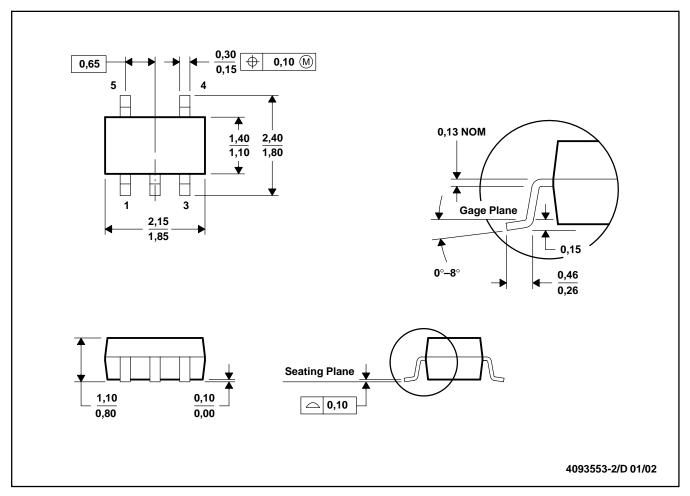
NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- C. Body dimensions do not include mold fla D. Falls within JEDEC MO—178 Variation AA. Body dimensions do not include mold flash or protrusion.



DCK (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE

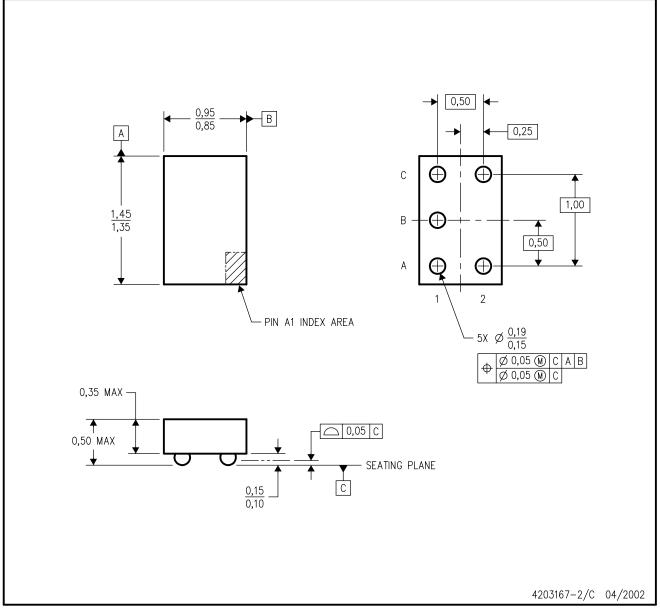


NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. Falls within JEDEC MO-203

YEA (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

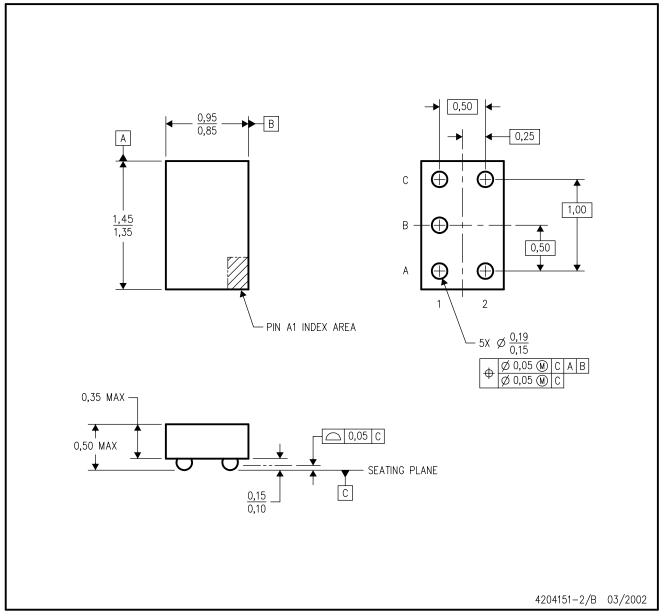
- B. This drawing is subject to change without notice.
- C. NanoStar™ package configuration.
- D. Package complies to JEDEC MO-211 variation EA.
- E. This package is tin-lead (SnPb). Refer to the 5 YZA package (drawing 4204151) for lead-free.

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YZA (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



NOTES: A. All line

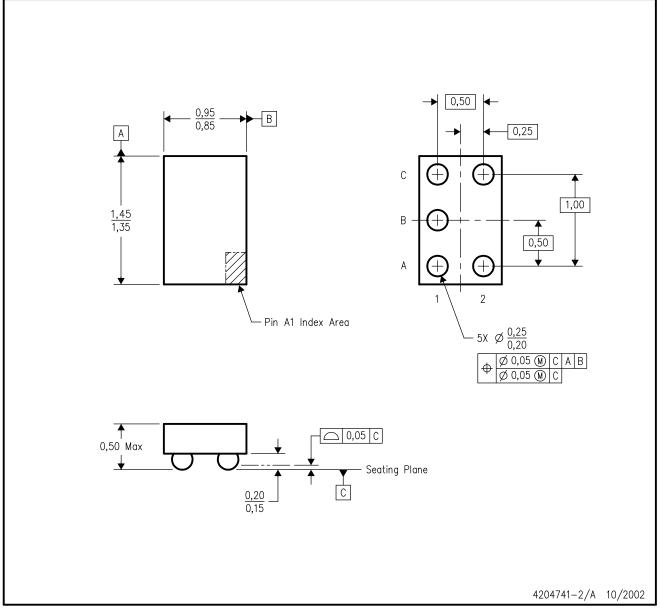
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. NanoFree $^{\text{TM}}$ package configuration.
- D. Package complies to JEDEC MO-211 variation EA.
- E. This package is lead-free. Refer to the 5 YEA package (drawing 4203167) for tin-lead (SnPb).

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YZP (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

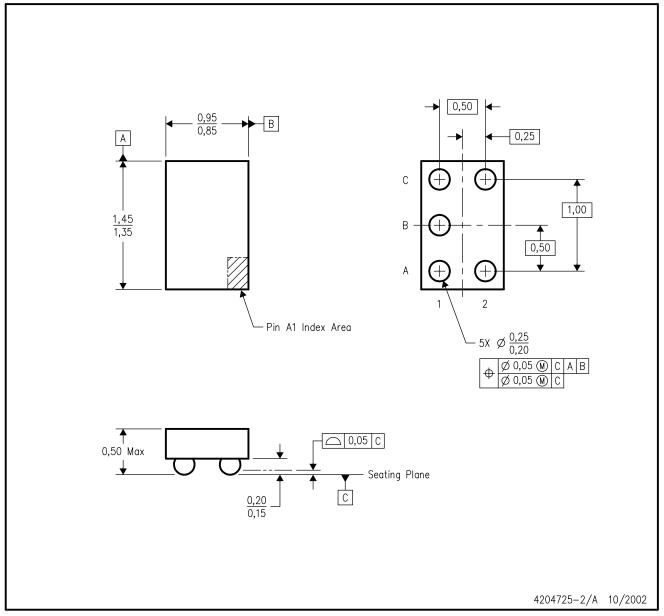
- B. This drawing is subject to change without notice.
- C. NanoFree $^{\text{TM}}$ package configuration.
- D. This package is lead-free. Refer to the 5 YEP package (drawing 4204725) for tin-lead (SnPb).

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YEP (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. NanoStar \mathbf{M} package configuration.
- D. This package is tin-lead (SnPb). Refer to the 5 YZP package (drawing 4204741) for lead-free.

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